

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
FuKui Precision Component (Shenzhen) Co., Ltd.	01/01/2017
Zhen Ding Technology Co., Ltd.	01/01/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	FuKui Precision Component (Shenzhen) Co., Ltd.
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<b>City:</b>	Shenzhen
<b>State/Country:</b>	CHINA
<b>Name:</b>	GARUDA TECHNOLOGY CO., LTD
<b>Street Address:</b>	4F., NO.156, SEC 1, ZHONGSHAN RD., BANQIAO DIST., NEW TAIPEI CITY 22065, TAIWAN (R.O.C)
<b>City:</b>	New Taipei
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Patent Number:</b>	8591692
<b>CORRESPONDENCE DATA</b>	
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<b>NAME OF SUBMITTER:</b>	ZHIGANG MA
<b>SIGNATURE:</b>	/Zhigang Ma/
<b>DATE SIGNED:</b>	01/17/2017
<b>Total Attachments: 3</b>	

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**ASSIGNMENT OF PATENT**

Atty Dkt No.:

WHEREAS, FUKUI PRECISION COMPONENT (SHENZHEN) CO., LTD. of YANLUO ROAD, BAO'AN DISTRICT, SHENZHEN, GUANGDONG, CHINA, is one of the owners of the entire right, title and interest of the U.S. Patents and Patent Applications listed in Exhibit A.

WHEREAS, ZHEN DING TECHNOLOGY CO., LTD. of NO. 6, LANE 28, SAN HO RD., SAN SHI VILLAGE, TAYUAN, TAoyUAN, TAIWAN, is one of the owners of the entire right, title and interest of the U.S. Patents and Patent Applications listed in Exhibit A.

WHEREAS, FUKUI PRECISION COMPONENT (SHENZHEN) CO., LTD., hereinafter referred to as "assignee" whose mailing address is YANLUO ROAD, BAO'AN DISTRICT, SHENZHEN, GUANGDONG, CHINA, is desirous of acquiring the entire right, title and interest in the same;

WHEREAS, GARUDA TECHNOLOGY CO., LTD., hereinafter referred to as "assignee" whose mailing address is 4F., NO.156, SEC. 1, ZHONGSHAN RD., BANQIAO DIST., NEW TAIPEI CITY 22065, TAIWAN, is desirous of acquiring the entire right, title and interest in the same;

NOW, THEREFORE, for good and valuable consideration, the receipt whereof is acknowledged, we, the patent and patent applications owners, by these presents do sell, assign and transfer unto said assignees the entire right, title and interest in and to the aforementioned Patents and Patent Applications; the same to be held and enjoyed by the said assignee for his own use and behoof, and for his legal representatives and assigns, to the full end of the term for which said Patents is granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this assignment day of Jan 1st, 2017, at Shenzhen, Guangdong, China

**FUKUI PRECISION COMPONENT (SHENZHEN) CO., LTD.**

By: SHEN CHANG-FANG  
Name: SHEN, CHANG-FANG  
Title: Chairman

**ZHEN DING TECHNOLOGY CO., LTD.**

By: SHEN CHANG-FANG  
Name: SHEN, CHANG-FANG  
Title: Chairman

Exhibit A

44 U.S. Patents and Patent Applications in total:

	Application No.	Patent No.	Title
1	11/847300	8009432	RETAINING APPARATUS FOR A FLEXIBLE PRINTED CIRCUIT BOARD
2	11/877585	7581312	METHOD FOR MANUFACTURING MULTILAYER FLEXIBLE PRINTED CIRCUIT BOARD
3	11/957324	8042265	METHOD FOR MANUFACTURING MULTILAYER FLEXIBLE PRINTED CIRCUIT BOARD
4	11/960656	7511962	FLEXIBLE PRINTED CIRCUIT BOARD
5	11/961241	8322017	COVERLAY PROCESSING SYSTEM
6	11/964578	7728232	PRINTED CIRCUIT BOARD ASSEMBLY HAVING ADHESIVE LAYER
7	11/967000	7903424	FLEXIBLE PRINTED CIRCUIT BOARD HOLDER
8	12/047152	8049113	PRINTED CIRCUIT BOARDS
9	12/051687	7943490	METHOD OF CUTTING PCBS
10	12/055587	7916499	APPARATUS FOR HOLDING PRINTED CIRCUIT BOARDS
11	12/106513	8071884	FLEXIBLE PRINTED CIRCUIT BOARD HAVING CURVED EDGE
12	12/110540	7872744	VISUAL INSPECTION APPARATUS FOR FLEXIBLE PRINTED CIRCUIT BOARDS
13	12/135873	8205330	METHOD FOR MANUFACTURING A PRINTED CIRCUIT BOARD
14	12/143632	8049511	METHOD OF DETECTING FAULTY VIA HOLES IN PRINTED CIRCUIT BOARDS
15	12/164422	8052881	METHOD OF MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARD HAVING BURIED HOLES
16	12/202551	8061959	BOARD INVERTER
17	12/253869	8071887	PRINTED CIRCUIT BOARD AND METHOD FOR MANUFACTURING SAME
18	12/270612	7789989	METHOD FOR MANUFACTURING RIGID-FLEXIBLE PRINTED CIRCUIT BOARD
19	12/274190	7987586	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD HAVING DIFFERENT THICKNESSES IN DIFFERENT AREAS
20	12/342205	8112880	METHOD FOR MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARDS
21	12/570040	8475867	METHOD FOR FORMING ELECTRICAL TRACES ON SUBSTRATE
22	12/766903	8388800	APPARATUS FOR WET PROCESSING SUBSTRATE
23	12/982881	8223505	FLEXIBLE PRINTED CIRCUIT BOARD HOLDER

24	13/091152	8516694	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD WITH CAVITY
25	13/116001	8978244	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD
26	13/116021	8481854	ELECTRONIC COMPONENT DEVICE AND CONNECTOR ASSEMBLY HAVING SAME
27	13/117159	8648261	PRINTED CIRCUIT BOARD
28	13/164776	8453321	METHOD FOR MANUFACTURING MULTILAYER FLEXIBLE PRINTED CIRCUIT BOARD
29	13/181453	9095082	METHOD FOR MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARD
30	13/192474	9125334	METHOD FOR MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARD
31	13/207438	8591692	METHOD FOR MANUFACTURING RIGID-FLEXIBLE PRINTED CIRCUIT BOARD
32	13/336008	8850701	METHOD FOR MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARD HAVING MOUNTING CAVITY
33	13/441932	9198304	METHOD FOR MANUFACTURING RIGID-FLEXIBLE PRINTED CIRCUIT BOARD
34	13/858102	9107311	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD
35	13/953881	9066431	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD WITH PATTERNED ELECTRICALLY CONDUCTIVE LAYER THEREIN VISIBLE
36	13/974382	9066417	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD
37	14/082196	9288914	METHOED OF MANUFACTUING A PRINTED CIRCUIT BOARD WITH CIRCUIT VISIBLE
38	14/095878	9210811	COMPACT RIGID-FLEXIBLE PRINTED CIRCUIT BOARD AND METHOD FOR MANUFACTURING SAME
39	14/140456	9072173	RIGID-FLEX PRINTED CIRCUIT BOARD AND METHOD FOR MAKING SAME
40	14/162769	9357631	FLEXIBLE PRINTED CIRCUIT BOARD AND METHOD FOR MAKING SAME
41	14/458236	\	PRINTED CIRCUIT BOARD AND METHOD FOR MANUFACTURING SAME
42	14/512546	\	HEAT DISSIPATION DEVICE AND A METHOD FOR MANUFACTURING SAME
43	14/586986	9277640	FLEXIBLE PRINTED CIRCUIT BOARD AND METHOD FOR MANUFACTURING SAME
44	14/691258	\	HEAT DISSIPATION DEVICE AND METHOD FOR MANUFACTURING SAME